

Title (en)
CURABLE RESIN COMPOSITION FOR COVERING A FINGERNAIL OR ARTIFICIAL FINGERNAIL

Title (de)
HÄRTBARE HARZZUSAMMENSETZUNG ZUR BESCHICHTUNG EINES FINGERNAGELS ODER EINES KÜNSTLICHEN FINGERNAGELS

Title (fr)
COMPOSITION DE RÉSINE DURCISSABLE POUR RECOUVRIR UN ONGLE OU UN ONGLE ARTIFICIEL

Publication
EP 2510920 A4 20150722 (EN)

Application
EP 10835949 A 20101207

Priority
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Abstract (en)
[origin: WO2011071029A1] Provided is a curable resin composition for covering a fingernail or artificial fingernail. Above all, said resin composition exhibits an excellent appearance after application, but is also highly resistant to water and abrasion, non-odorous, non-damaging to the fingernail, and hypoallergenic. The provided resin composition therefore both is highly safe with respect to the human body and has excellent storage stability. The resin composition contains (A) a water-based emulsion of a polymer that contains a functional group that can undergo a polymerization reaction upon irradiation with active energy rays, (B) polyethylene glycol, and (C) a photo-radical polymerization initiator (the molecules of which do not contain nitrogen atoms).

IPC 8 full level
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Citation (search report)
• [A] DE 102005063061 A1 20070705 - COSTRADE BEAUTY CONSULTING GMB [AT]
• [A] US 2002197218 A1 20021226 - BERNARD PASCALE [FR], et al
• See references of WO 2011071029A1

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